

Accounting for deviation of a test fixture from the reference

(in support of comment #407)

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Problem statement

- The method of accounting for the difference between the reference and actual test fixture insertion loss is not specified.
- It was suggested to use the “de-embed and re-embed” method. This would effectively be a calibration procedure.
 - The process of de-embedding s-parameters is known in the industry, implemented in test equipment and used in many practical tests. It does not need a detailed specification.
 - The contribution [heck_3dj_01_2607](#) includes suitable text for describing the procedure.
- The re-embedding part requires S-parameters for the reference HCB and MCB that match the magnitude of the insertion loss (existing equations 179B–1 and 179B–2).
 - It would be good to represent these S-parameters as a mathematical model using the methods of Annex 93A.

Outline of this presentation

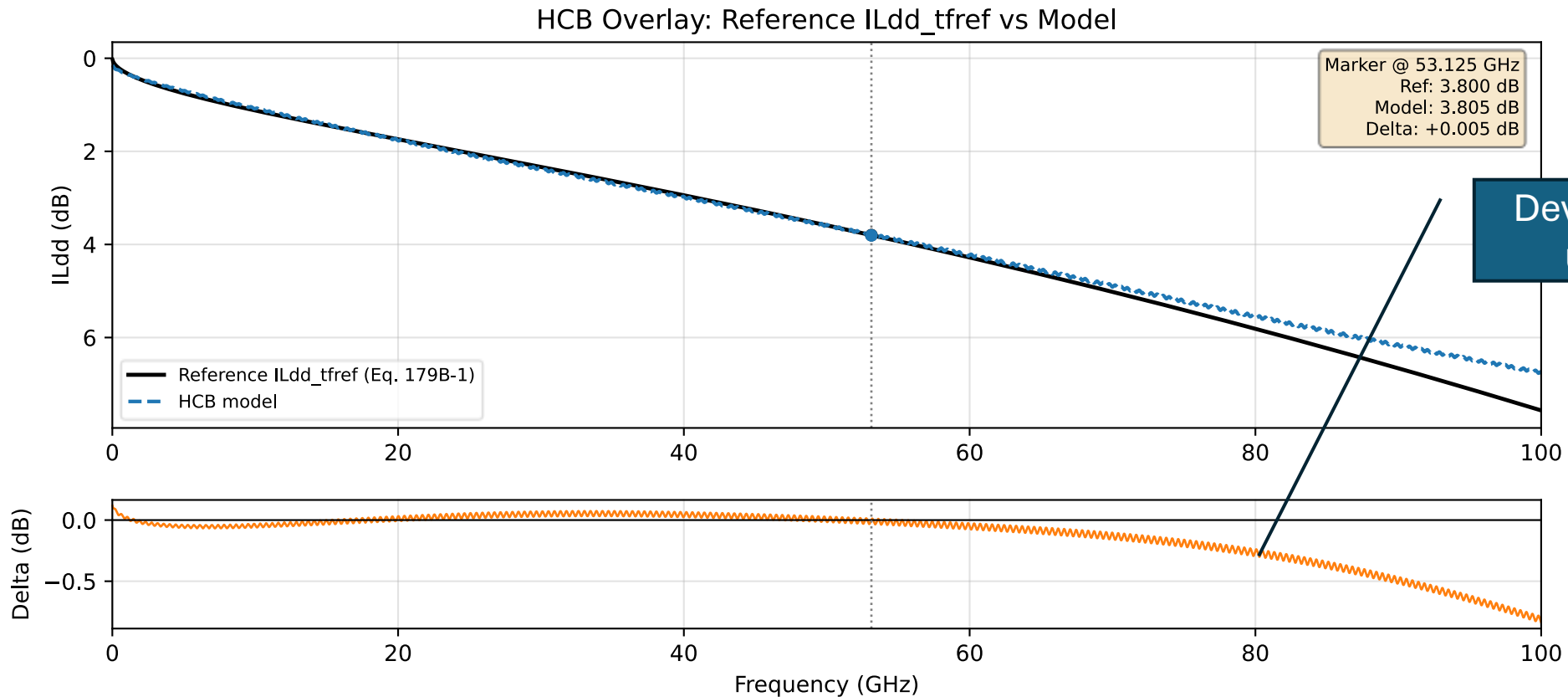
- Proposed models of the reference MCB and HCB; showing
 - The fit to the reference ILdd of each one, and the mated fixtures
 - Model structure and parameters
 - TDR of the MTF (concatenated models) from both sides
- Proposed text for Annex 179B

Rationale for models

- The model should match the ILdd equations and be representative of physical dimensions of HCB and MCB.
- Physical dimensions were estimated from TDR calculation based on data from [mammenga_3dj_02_2601](#) (contributed OSFP test fixture data).
- Goal was to fit the reference ILdd magnitude to a good degree, while forcing the lengths of the major elements to the estimated values.
- The same γ_0 , a_1 , a_2 (loss per mm) and τ were used for all segments of each model (HCB or MCB).
 - This may not match real design.
- Capacitor models were added to improve matching at high frequencies.
- The models are not intended to match recent designs – the intent is to match the reference equations!

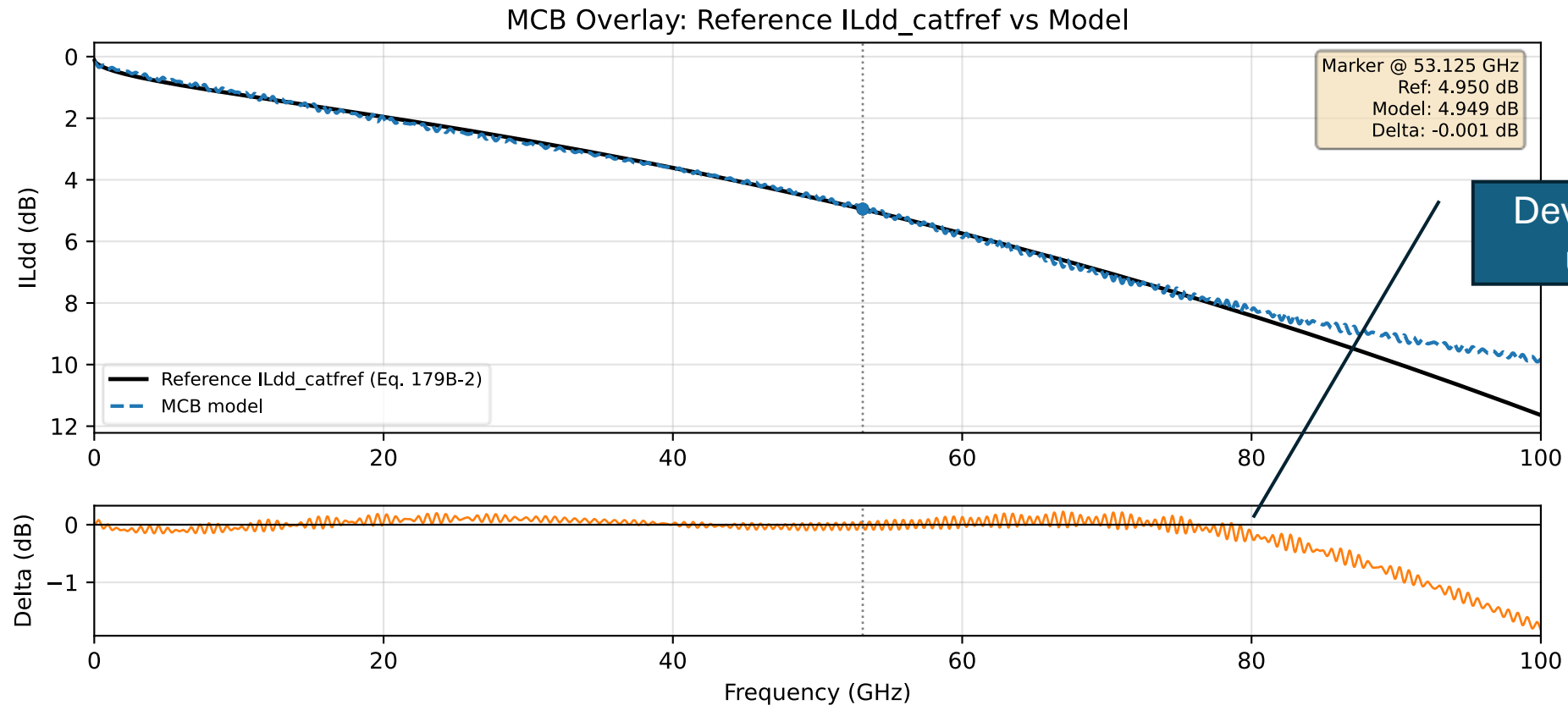
HCB model fit results

ILdd calculated with respect to single-ended impedance of 46.25 Ω



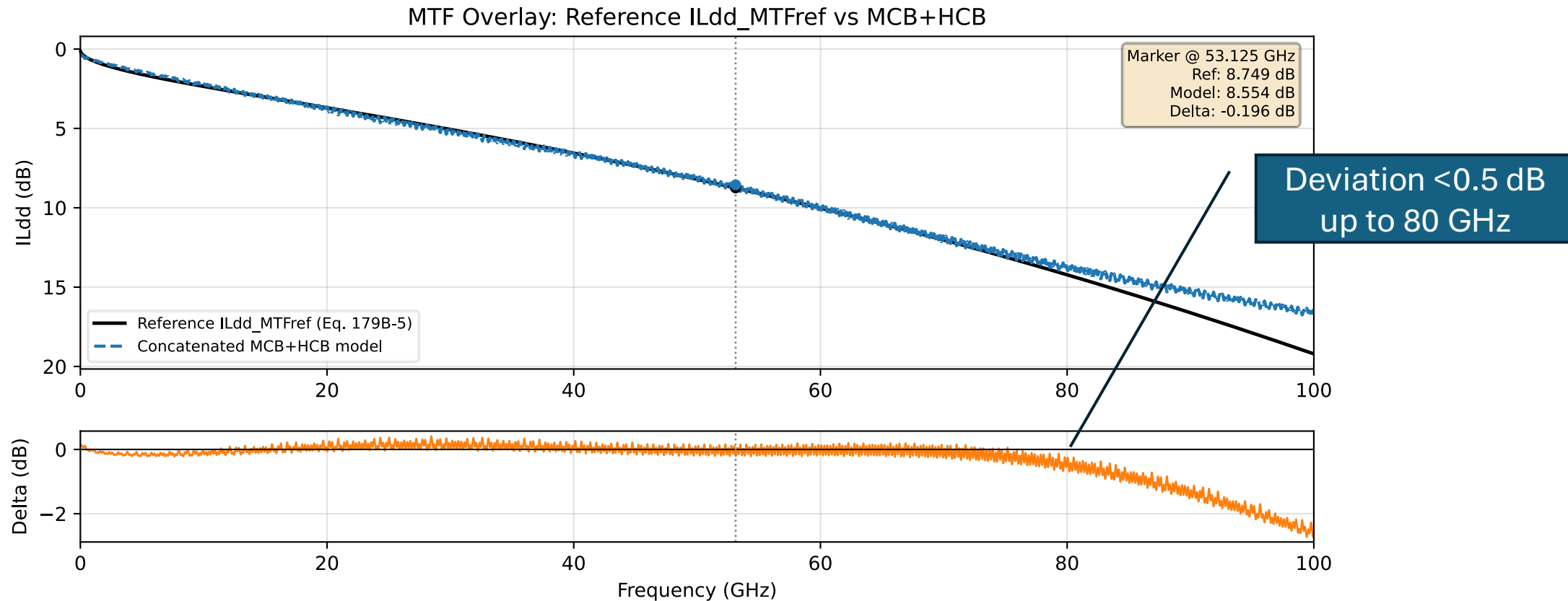
MCB model fit results

ILdd calculated with respect to single-ended impedance of $46.25\ \Omega$

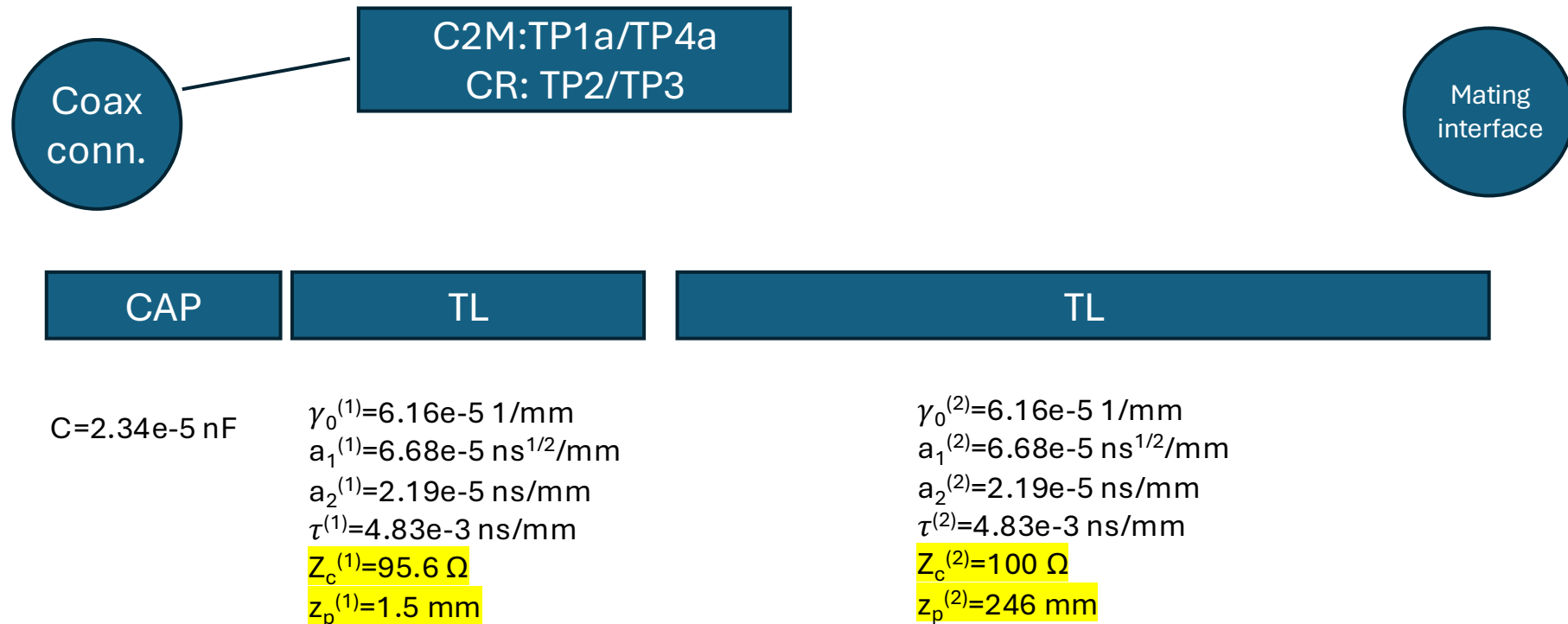


MTF model fit results

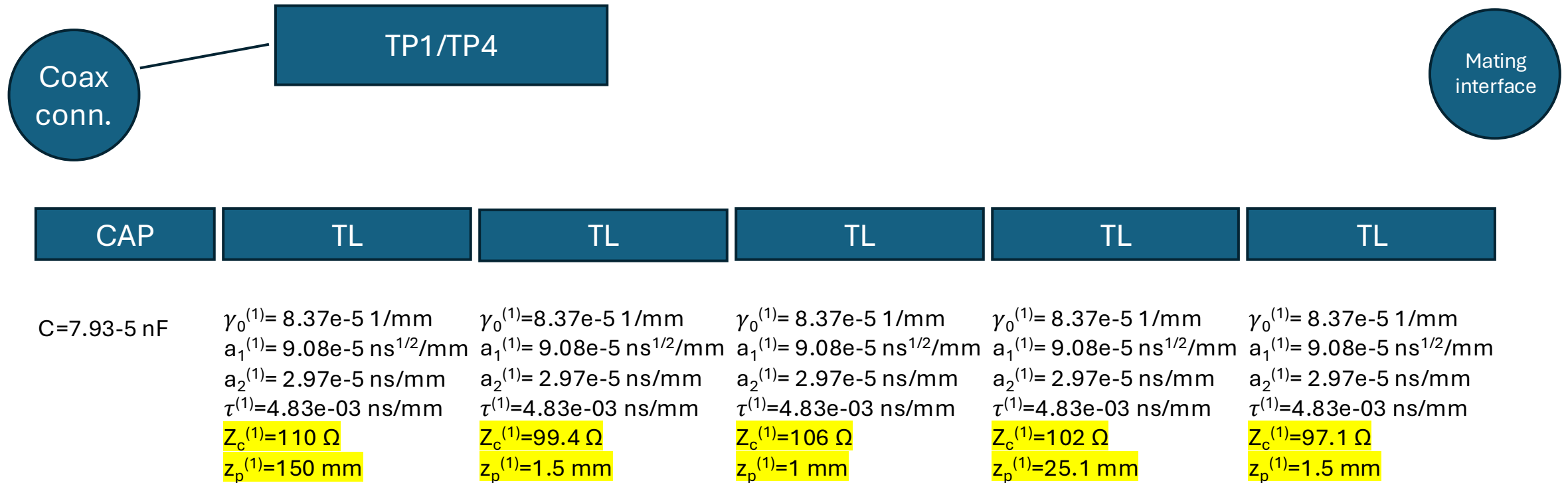
ILdd calculated with respect to single-ended impedance of 46.25 Ω



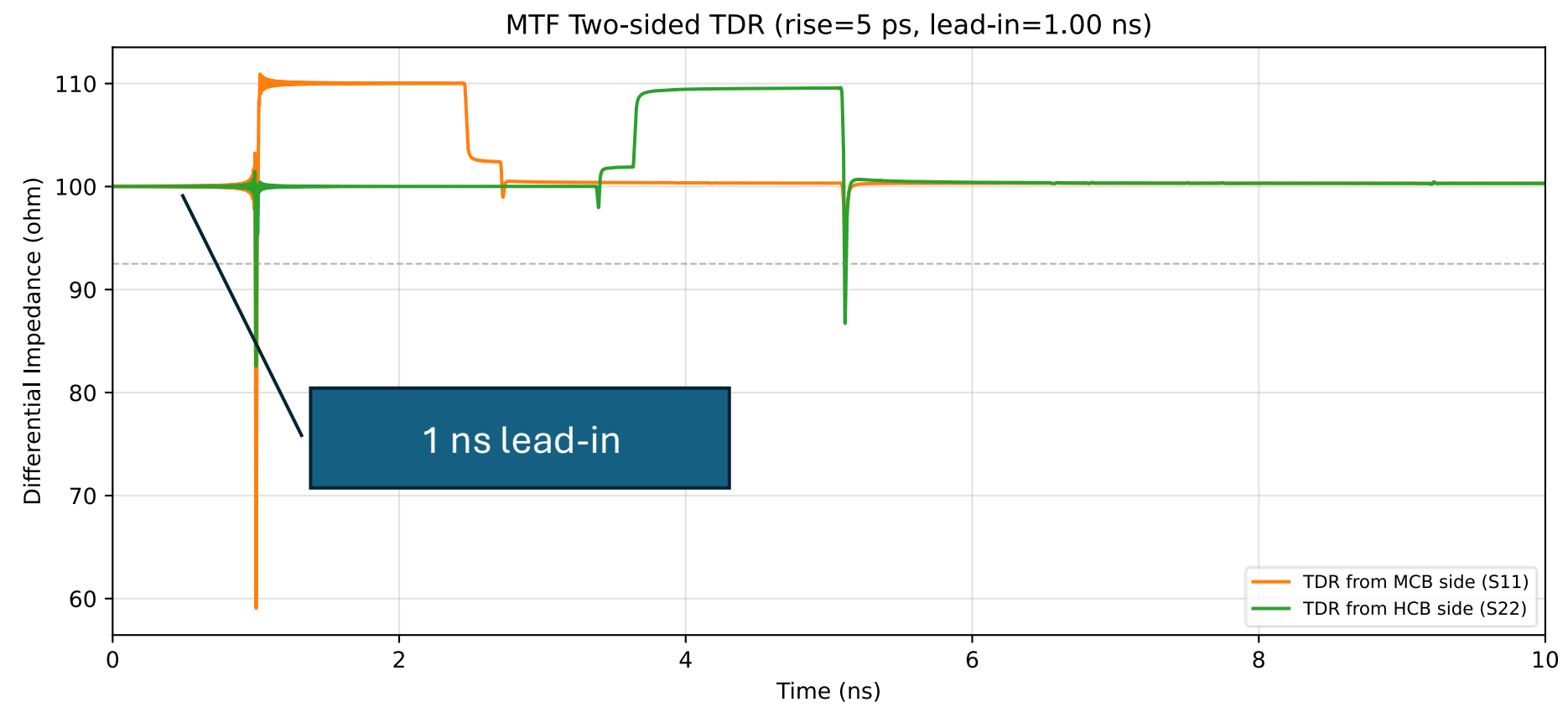
HCB model structure and parameters



MCB model structure and parameters



TDR plots



Proposed text changes (HCB)

Implement with editorial license

- In 179B.2.1, add the following text and new equation at the end:

The reference insertion loss is approximately achieved by scattering parameters generated by equation (179B-X1) :

$$S = \text{cascade}(S(C_1), S(TL_1), S(TL_2)) \quad (179B-X1)$$

Where

$S(C_1)$ are the S-parameters for a shunt capacitor C_1 with value in Table 179B-X2, as defined in [93A.1.2.2](#)

$S(TL_1)$ and $S(TL_2)$ are the S-parameters for transmission lines with parameters in Table 179B-X2, as defined in [93A.1.2.4](#)

- Add new table 179B-X2 with C and TL parameters from slide 8.

Proposed text changes (MCB)

Implement with editorial license

- In 179B.3.1, add the following text and new equation at the end:

The reference insertion loss is approximately achieved by scattering parameters generated by Equation 179B-X3 :

$$S = \text{cascade}(S(C_1), S(TL_1), S(TL_2), S(TL_3), S(TL_4), S(TL_5)) \quad (179B-X3)$$

Where

$S(C_1)$ are the S-parameters for a shunt capacitor C_1 with value in Table 179B-X4, as defined in [93A.1.2.2](#)

$S(TL_1)$ through $S(TL_5)$ are the S-parameters for transmission lines with parameters in Table 179B-X4, as defined in [93A.1.2.4](#)

- Add new table 179B-X4 with C and TL parameters from slide 9.